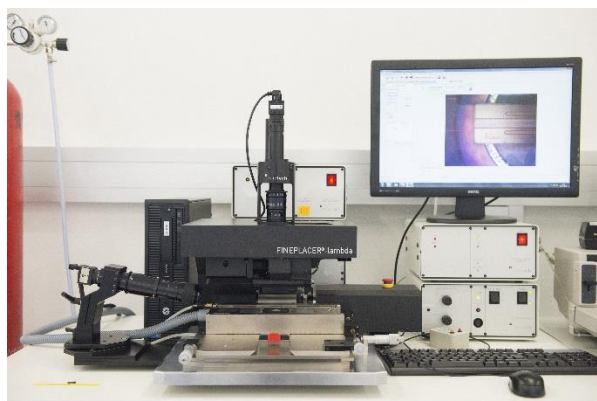


PACKAGING & ASSEMBLY

Die Bonder

Manufacturer: finetech

Model: FINEPLACER lambda



General Description:

The FINEPLACER lambda is a flexible sub-micron bonder used for precise placement, die attach and advanced packaging. The system offers outstanding flexibility with a modular design and can be easily reconfigured for different applications.

The system offers outstanding flexibility with a modular design and can be easily reconfigured for different applications. It is the ideal choice for low volume production, prototyping, education and R&D where process flexibility is the key.

Key Specifications:

- Sub- micron placement accuracy
- Handles ultra-small components, special tools allow object sizes > 5 µm
- Supported substrate size up to 6"
- Small footprint and compact design

Availability	Use allowed for all researchers with permission
Location	Cleanroom Europastraße 12 9524 Villach
Responsibles / Contact	Dr. Ali Roshanghias / Dr. Jochen Bardong Tel.:+43 4242 56300 256